SMBG Plastic-Encapsulate Diodes

Fast Recovery Rectifier Diode

Features

- I_O 2A
- VRRM 50V-1000V
- High surge current capability
- Glass passivated chip
- Polarity: Color band denotes cathode

Applications

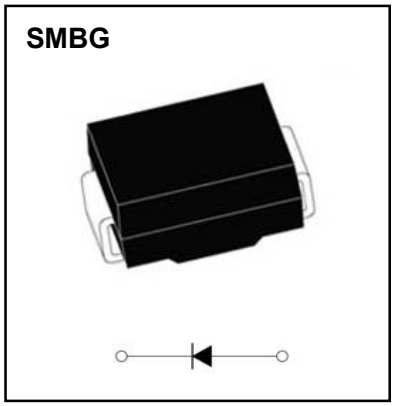
- Rectifier

Marking

- RS2X

  X：From A To M

SMBG



Limiting Values (Absolute Maximum Rating)

Item	Symbol	Unit	Test Conditions	RS2						
				A	B	D	G	J	K	M
Repetitive Peak Reverse Voltage	V_{RRM}	V		50	100	200	400	600	800	1000
Maximum RMS Voltage	V_{RMS}	V		35	70	140	280	420	560	700
Average Forward Current	$I_{F(AV)}$	A	60Hz Half-sine wave, Resistance load, Ta=75℃	2.0						
Surge(Non-repetitive)Forward Current	I_{FSM}	A	60Hz Half-sine wave,1 cycle, Ta =25℃	60						
Junction Temperature	T_J	℃		-55~+150						
Storage Temperature	T_{STG}	℃		-55 ~ +150						

Electrical Characteristics (T_a=25℃ Unless otherwise specified）

Item	Symbol	Unit	Test Condition		RS2						
					A	B	D	G	J	K	M
Peak Forward Voltage	V_F	V	I_F=2.0A		1.3						
Maximum reverse recovery time	t_{rr}	ns	I_F=0.5A,I_R=1.0A,I_{rr}=0.25A		150				250	500	
Peak Reverse Current	I_{RRM1}	μA	V_{RM}=V_{RRM}	T_a =25℃	2.5						
	I_{RRM2}			T_a =125℃	200						
Thermal Resistance(Typical)	$R_{\theta J-A}$	℃/W	Between junction and ambient		50[1)]						
	$R_{\theta J-L}$		Between junction and terminal		40[1)]						

Notes:

Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.27" x 0.27" (7.0 mm x 7.0 mm)er copper pad areas

Typical Characteristics

FIG.1 : FORWARD CURRENT DERATING CURVE

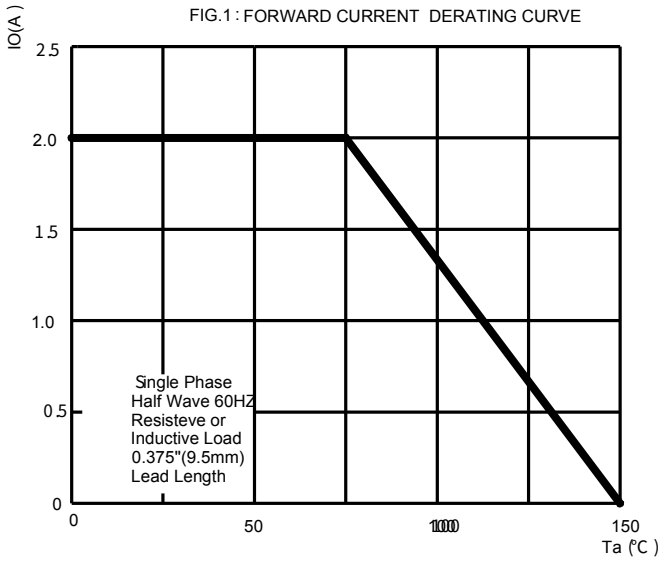


FIG.2 : MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

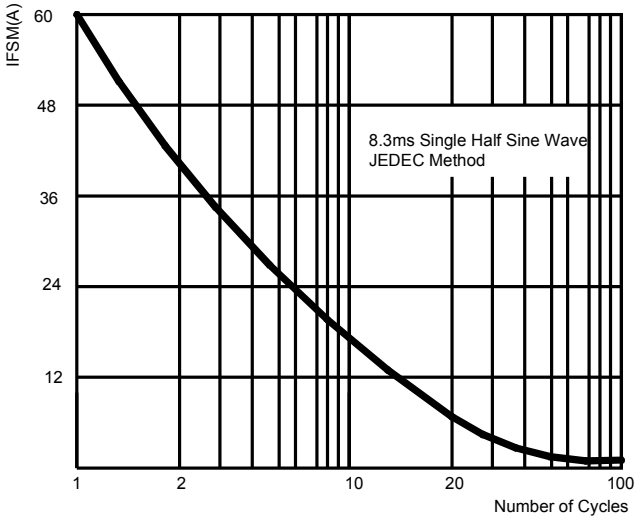


FIG.3: TYPICAL FORWARD CHARACTERISTICS

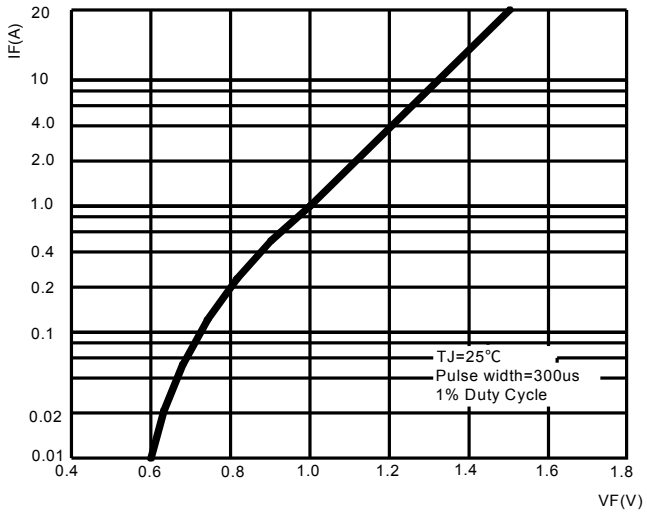


FIG.4 : TYPICAL REVERSE CHARACTERISTICS

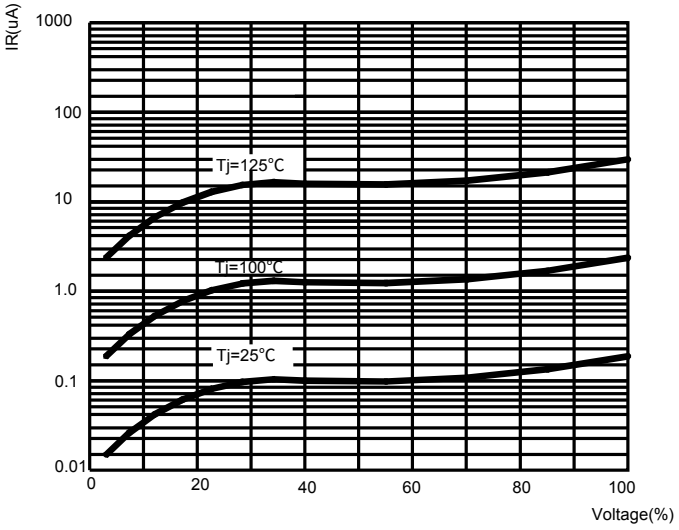
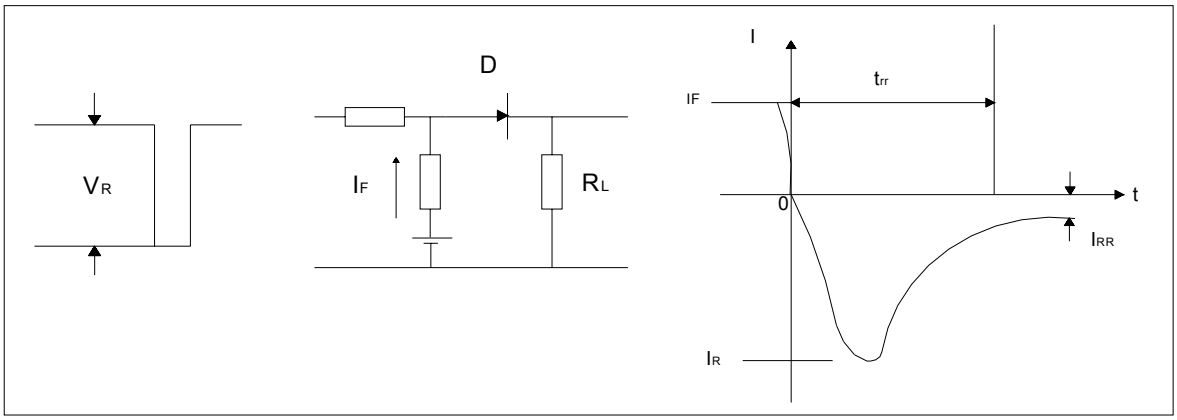
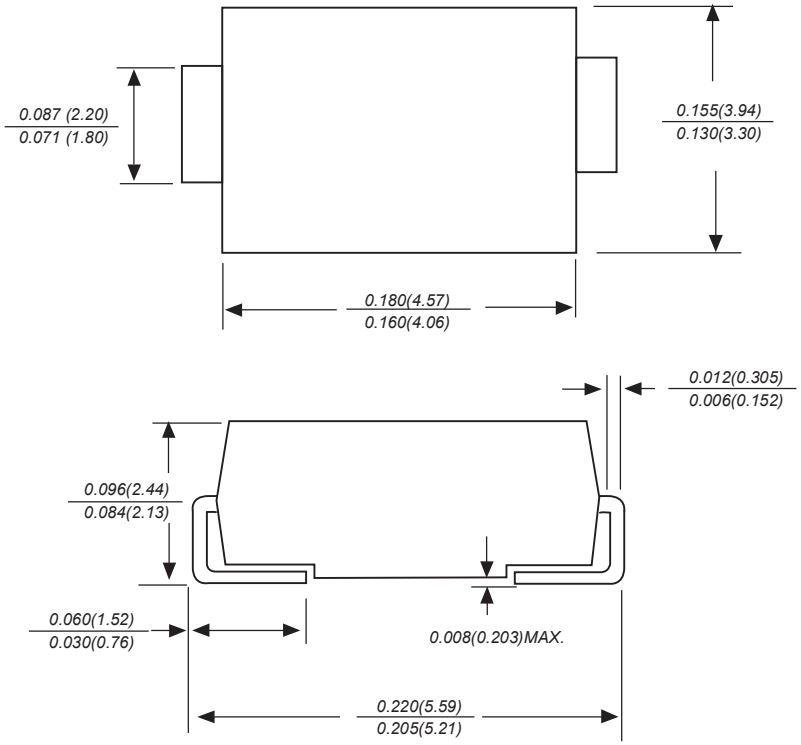


FIG.5: Diagram of circuit and Testing wave form of reverse recovery time

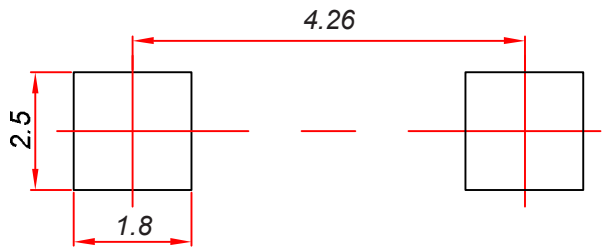


SMBG Package Outline Dimensions



Dimensions in inches and (millimeters)

SMBG Suggested Pad Layout



Note:
1.Controlling dimension:in millimeters.
2.General tolerance:± 0.05mm.
3.The pad layout is for reference purposes only.

Reel Taping Specifications For Surface Mount Devices-SMBG

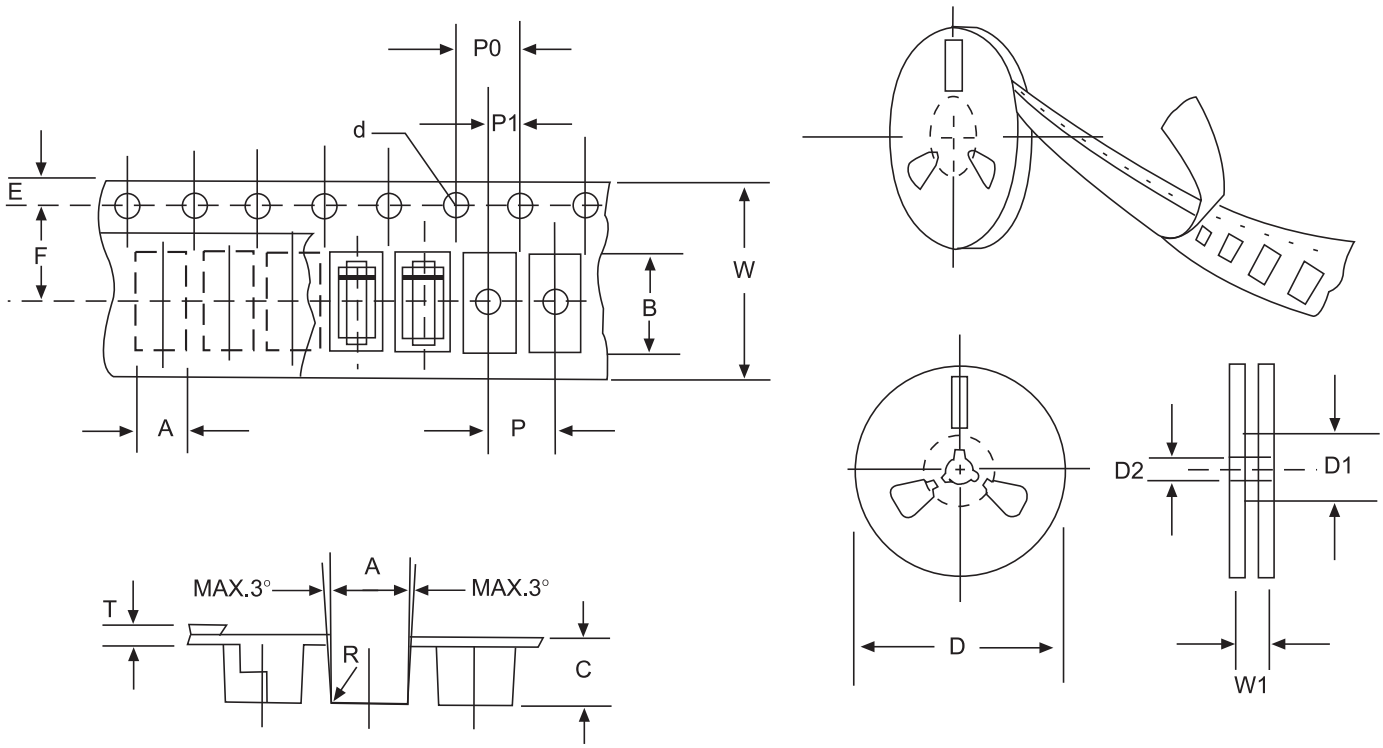


FIG:CONFIGURATION OF AXIAL TAPING

ITEM	SYMBOL	SMBGmm(inch)
Carrier width	A	4.09±0.1(0.161±0.004)
Carrier length	B	5.82±0.1(0.229±0.004)
Carrier depth	C	3.33±0.1(0.131±0.004)
Sprocket hole	d	1.55±0.05(0.061±0.0002
Reel outside diameter	D	330/178±2.0(13/7.0±0.79)
Reel inner diameter	D1	8.0±0.2(0.315±0.008)
Feed hole diameter	D2	13±0.5(0.512±0.020)
Stroket hole position	E	1.75±0.1(0.069±0.004)
Punch hole position	F	5.65±0.05(0.222±0.002)
Punch hole pitch	P	8.0±0.1(0.315±0.004)
Sprocket hole pitch	P0	4.0±0.1(0.157±0.004)
Embossment center	P1	2.0±0.1(0.079±0.004)
Totall tape thickness	T	0.32±0.1(0.013±0.004)
Tape width	W	12.0±0.2(0.472±0.008)
Reel width	W1	16.8±2.0(0.661±0.079)

NOTE:Devices are packde in accordance with EIA standard RS-481-A and specification given above.